

SPECIFICATION

Product Name:_	ame: <u>IOT Module</u>	
Model No.:	TI7100CB1	_
Туре:	URAT Interface	
Version:	V1.0	
Date:	2022/2/22	

Shenzhen Trolink Technology Co., Ltd

Add:2F, B block, The first Techno park of Huafeng, Gushu, Baoan District, Shenzhen, China.

Tel: 0755-88828355/83224500

Website: http://en.tro-link.com/ Email:sales@trolink.cn





Content

1. Profile	.3
2. Product Characteristic	. 3
3. Product Picture	.3
4. Chip Block Diagram	.4
5. Wireless Module Outline	4
6. Pin Assignments	5
7. Electrical Characteristic	6
8. RF Parameter	6
9. DC Consumption	7
10. Reference design for PCBA	
11. Weld and storage environment	8
12. Package details	8



1. Profile

TI7100CB1 is an intelligent new generation of highly integrated Wi-Fi and BLE combination chip TG7100C. The wireless subsystem includes 2.4G RF, Wi-Fi 802.11b/g/n and BLE baseband/MAC design. The microcontroller subsystem includes a low-power 32-bit RISC CPU, cache and memory. The power management unit provides flexible settings to achieve low power consumption mode and supports multiple security functions. This Demo board is designed based on TG7100C and can be debugged by JTAG. It provides rich hardware interfaces including UART, PWM, ADC, DAC, I2C, SPI, GPIO, SDIO, etc.

2. Product Characteristic

- 802.11b/g/n 1*1 standard
- WiFi+BLE 5.0 Combo, Support STA, Soft AP mode and Sniffer mode
- ullet Open source independent controllable RISC-V CPU, 1 \sim 160MHz adjustable, 276KB SRAM;
- Ultra long distance, the maximum transmission power is 21dBm, the sensitivity is -98dBm, and more than one wall is penetrated;
- High security: support safe startup, safe debugging, AES 128/192/256, Encryption engine, WPA3, MD5, SHA-1/224/256', PKA(RSA/ECC)
- Support the coexistence of Wi-Fi and BLE

3. Product Picture



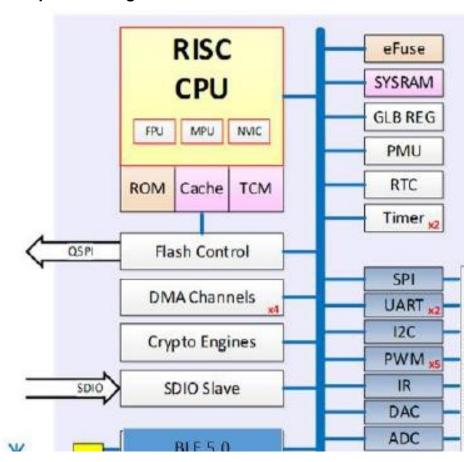


(BOTTOM)

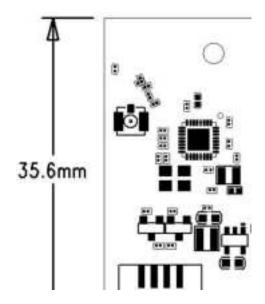




4. Chip Block Diagram

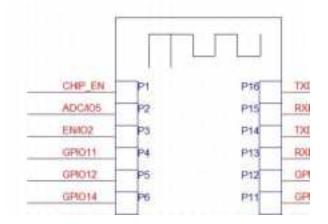


5. Wireless Module Outline





6.Pin Assignments



NO	Pin Name	Description	
1	Chip_EN	Chip enable pin (active high)	
2	GPIO5	ADC	
3	GPIO2	EN	
4	GPIO11	GPI011	
5	GPIO12	GPIO12	
6	GPIO14	GPIO14	
7	GPIO17	GPIO17	
8	VCC	Power supply 3.3V is required	
9	GND	Ground	
10	GPIO0	GPIO0	
11	GPIO8	GPIO8 (Boot option)	
12	GPIO1	GPIO1	
13	GPIO3	RXD (5V) Communication serial port	
14	GPIO4	TXD(5V)Communication serial port	
15	GPIO16	RXD(3.3V) Burning serial port	
16	GPIO7	TXD(3.3V) Burning serial port	



7. Electrical Characteristic

Item	Description
Model No.	TI7100CB1
Chipset	TG7100C
Interface	URAT
Frequency Band.	2.4 – 2.483.5MHz
WiFi Standard	IEEE 802.11b/g/n
Modulation Mode	802.11b: CCK, DQPSK, DBPSK 802.11g: 64-QAM, 16-QAM, QPSK BPSK 802.11n:64-QAM,16QAM,QPSK, BPSK
Transmit Power	1,2,5.5,6,11,12,18,22,24,30,36,48,54,65,,72.2Mbps
Module Size	35.6*21.6*0.8mm(L*W*H)
Working Voltage.	DC 5V
Encryption method	AES 128/192/256 WPA3, MD5.,SHA-1/224/256, PKA(RSA/ECC)
Working Temp	-230°C to +85°C
Storage Temp	-55°C to +85°C

8. RF Parameter

	802.11b:17±1.5dBm
Transmit power	802.11g:15±1.5dBm
	802.11n HT20:14±1.5dBm
	802.11b: <-20dB@11Mbps
EVM	802.11g: <-27dB@54Mbps
	802.11nHT20:< -28dB@65Mbps
Receiving sensitivity	11b-1Mbps: -98dBm
	11b-11Mbps: -91dBm
	11g-54Mbps: -77dBm
	11n HT20-MCS0: -92dBm
	11n HT20-MCS7: -73dBm

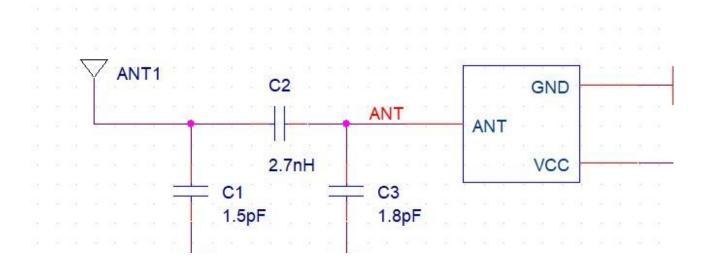


9. DC Consumption

Test condition: DC3.3V ; Temperature 25°C Unit: mA			
Mode	TX/RX	Current consumption	
802.11b (11Mbps)	TX	132	
	RX	35	
802.11g (54Mbps)	TX	120	
	RX	37	
802.11n HT20 (MCS7)	TX	108	
	RX	37	

10. Reference design for PCBA

Circuit design



Requirement about layout of PCB

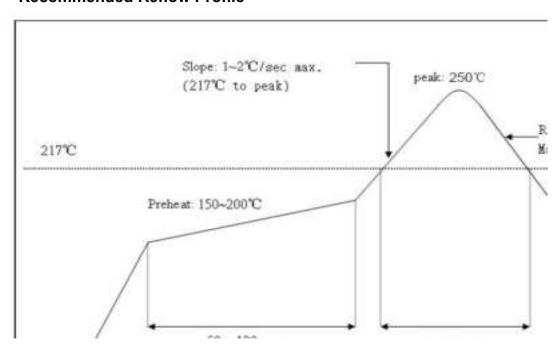
a. RF layout needs to be grounded and 50 ohm impedance



11. Environment about Working and Storage

Working Temp	Temperature:-30°Cto+85°C Relative Humidity:10-90%(non-condensing)
Storage Temp	Temperature:-55°Cto+85°C(non-condensing) Relative Humidity:10-90%(non-condensing)

Recommended Reflow Profile



Heating Stage : Temp : <150 $^{\circ}$ C , Time : 60 \sim 90/sec, Ramp rate: 1 \sim 3 $^{\circ}$ C/S

Preheat Range : Temp : $150^{\circ}\text{C} \sim 200^{\circ}\text{C}$, Time : 60-120/sec, Ramp rate : 0.3-0.8

Reflow Stage : Peak temp:235 $^{\circ}$ C ~250 $^{\circ}$ C (advise peak temp < 245 $^{\circ}$ C) $^{\circ}$ Time:30-70 /sec

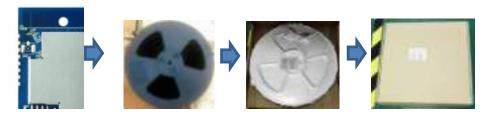
Cooling Stage : Temp : 217 ℃ ~170 ℃ , ramp rate: 3~5 ℃/S . Sn&Ag&Cu Lead-free solder(SAC305)

12. Package details

Packed as vacuum reel

• Reel color: blue Carton size: 33.7cm*33.7cm*9.5cm

2 packs desiccant, 1 pcs humidity card



FCC STATEMENT

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: This device may not cause harmful interference, and

This device must accept any interference received, including interference that may cause undesired operation.

Warning: Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed

and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

Reorient or relocate the receiving antenna.

Increase the separation between the equipment and receiver.

Connect the equipment into an outlet on a circuit different from that to which the receiver is connected. Consult the dealer or an experienced radio/TV technician for help.

FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01

2.2 List of applicable FCC rules

FCC Part 15 Subpart C 15.247 & 15.207 & 15.209

2.3 Specific operational use conditions

Operation Frequency:BLE: 2402~2480MHz; WIFI: 2412~2462MHz

Number of Channel: BLE: 40 Channels; WIFI: 11 Channels

Modulation Type:BLE: GFSK; WIFI: 802.11b: DSSS (CCK, DQPSK, DBPSK)

802.11g: OFDM (BPSK, QPSK, 16QAM, 64QAM)

802.11n: OFDM (BPSK, QPSK, 16QAM, 64QAM)

Antenna Type:PCB antenna

Antenna Gain(Peak):3.54 dBi (Provided by customer)

The module can be used for mobile or portable applications with a maximum 3.54dBi antenna. The host manufacturer installing this module into their product must ensure that the final composit product complies with the FCC requirements by a technical assessment or evaluation to the FCC rules, including the transmitter operation. The host manufacturer has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as show in this manual.

2.4 Limited module procedures

Not applicable. The module is a Single module and complies with the requirement of FCC Part 15.212.

2.5 Trace antenna designs

Not applicable. The module has its own antenna, and doesn't need a host's printed board microstrip trace antenna etc.



2.6 RF exposure considerations

The module must be installed in the host equipment such that at least 20mm is maintained between theantenna and users' body; and if RF exposure statement or module layout is changed, then the host product manufacturer required to take responsibility of the module through a change in FCC ID or new application. The FCC ID of the module cannot be used on the final product. In these circumstances, the host manufacturer will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

2.7 Antennas

Antenna Specification are as follows:

Antenna Type:PCB antenna

Antenna Gain(Peak):3.54 dBi (Provided by customer)

This device is intended only for host manufacturers under the following conditions:

The transmitter module may not be co-located with any other transmitter or antenna;

The module shall be only used with the External antenna(s) that has been originally tested and certified with this module. The antenna must be either permanently attached or employ a 'unique' antenna coupler.

As long as the conditions above are met, further transmitter test will not be required. However, the host manufacturer is still responsible for testing their end-product for any additional compliance requirements required with this module installed (for example, digital device emissions, PC peripheral requirements, etc.).

2.8 Label and compliance information

Host product manufacturers need to provide a physical or e-label stating "Contains FCC ID 2AYHW-TI7100CB1 With their finished product.

2.9 Information on test modes and additional testing requirements

Operation Frequency:BLE: 2402~2480MHz; WIFI: 2412~2462MHz

Number of Channel: BLE: 40 Channels; WIFI: 11 Channels

Modulation Type:BLE: GFSK; WIFI: 802.11b: DSSS (CCK, DQPSK, DBPSK)

802.11g: OFDM (BPSK, QPSK, 16QAM, 64QAM) 802.11n: OFDM (BPSK, QPSK, 16QAM, 64QAM)

Antenna Type:PCB antenna

Antenna Gain(Peak):3.54 dBi (Provided by customer)

Host manufacturer must perfom test of radiated & conducted emission and spurious emission, etc according to the actual test modes for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product.

Only when all the test results of test modes comply with FCC requirements, then the end product can be sold legally.

2.10 Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is **only** FCC authorized for FCC Part 15 Subpart C 15.247 & 15.207 & 15.209 and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product as being Part 15 Subpart B compliant (when it also contains unintentional-radiator digital circuity), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed.